## TP3064, TP3067

Enhanced Serial Interface CMOS CODEC/Filter COMBO



Literature Number: SNAS570

# TP3064, TP3067 "Enhanced" Serial Interface CMOS CODEC/Filter COMBO®

### **General Description**

The TP3064 ( $\mu$ -law) and TP3067 (A-law) are monolithic PCM CODEC/Filters utilizing the A/D and D/A conversion architecture shown in *Figure 1*, and a serial PCM interface. The devices are fabricated using National's advanced double-poly CMOS process (microCMOS).

Similar to the TP305X family, these devices feature an additional Receive Power Amplifier to provide push-pull balanced output drive capability. The receive gain can be adjusted by means of two external resistors for an output level of up to  $\pm 6.6 V$  across a balanced  $600\Omega$  load.

Also included is an Analog Loopback switch and a  $\overline{\mathsf{TS}_X}$  output.

See also AN-370, "Techniques for Designing with CODEC/Filter COMBO Circuits."

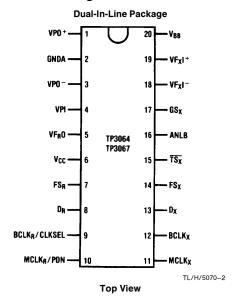
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### **Features**

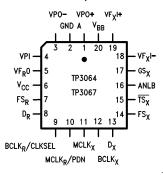
- Complete CODEC and filtering system including:
  - Transmit high-pass and low-pass filtering
  - Receive low-pass filter with sin x/x correction
  - Active RC noise filters
  - μ-law or A-law compatible COder and DECoder
  - Internal precision voltage reference
  - Serial I/O interface
  - Internal auto-zero circuitry
  - Receive push-pull power amplifiers
- μ-law—TP3064
- A-law—TP3067
- Designed for D3/D4 and CCITT applications
- ±5V operation
- Low operating power—typically 70 mW
- Power-down standby mode—typically 3 mW
- Automatic power-down
- TTL or CMOS compatible digital interfaces
- Maximizes line interface card circuit density

# Block Diagram ANALOG VF<sub>X</sub>| NYD RC AUTO-ZERO VF<sub>X</sub>| VF<sub>X</sub>| VF<sub>Y</sub>| NECENSION OF TRUE ONC CAMACTION RC AUTO-ZERO ONC CHARGE S'/H ONC COMPARATOR ONC COMPA

### **Connection Diagrams**



### **Plastic Chip Carrier**



Top View

TL/H/5070-6

Order Number TP3064J or TP3067J See NS Package J20A

Order Number TP3064WM or TP3067WM See NS Package M20B

Order Number TP3064N or TP3067N See NS Package N20A

Order Number TP3064V or TP3067V See NS Package V20A

### **Pin Description**

I III De	Scription		
Symbol VPO+ GNDA	Function  The non-inverted output of the receive power amplifier.  Analog ground. All signals are referenced to this pin.	Symbol MCLK <sub>X</sub>	Function  Transmit master clock. Must be 1.536 MHz, 1.544 MHz or 2.048 MHz. May be asynchronous with MCLK <sub>R</sub> . Best performance is realized from synchronous operation.
VPO-	The inverted output of the receive power amplifier.	BCLK <sub>X</sub>	The bit clock which shifts out the PCM data on $D_X$ . May vary from 64 kHz to 2.048 MHz,
VPI VF <sub>R</sub> O V <sub>CC</sub>	Inverting input to the receive power amplifier.  Analog output of the receive filter.  Positive power supply pin. $V_{CC} = +5V \pm 5\%$ .	$D_X$	but must be synchronous with MCLK <sub>X</sub> .  The TRI-STATE® PCM data output which is enabled by FS <sub>X</sub> .
FS <sub>R</sub>	Receive frame sync pulse which enables $\operatorname{BCLK}_R$ to shift PCM data into $\operatorname{D}_R$ . FS $_R$ is an 8 kHz pulse train. See <i>Figures 2</i> and 3 for timing details.	FS <sub>X</sub>	Transmit frame sync pulse input which enables $BCLK_X$ to shift out the PCM data on $D_X$ . $FS_X$ is an 8 kHz pulse train, see <i>Figures 2</i> and <i>3</i> for timing details.
$D_R$	Receive data input. PCM data is shifted into D <sub>R</sub> following the FS <sub>R</sub> leading edge.	TS <sub>X</sub>	Open drain output which pulses low during the encoder time slot.
BCLK <sub>R</sub> / CLKSEL	The bit clock which shifts data into D <sub>R</sub> after the FS <sub>R</sub> leading edge. May vary from 64 kHz to 2.048 MHz. Alternatively, may be a logic input which selects either 1.536 MHz/1.544 MHz or 2.048 MHz for master clock in synchronous mode and	ANLB	Analog Loopback control input. Must be set to logic '0' for normal operation. When pulled to logic '1', the transmit filter input is disconnected from the output of the transmit preamplifier and connected to the VPO+output of the receive power amplifier.
	$BCLK_X$ is used for both transmit and receive directions (see Table I).	GS <sub>X</sub>	Analog output of the transmit input amplifier. Used to externally set gain.
MCLK <sub>R</sub> / PDN	Receive master clock. Must be 1.536 MHz, 1.544 MHz or 2.048 MHz. May be asynchronous with MCLK <sub>X</sub> , but should be	VF <sub>X</sub> I <sup>-</sup> VF <sub>X</sub> I <sup>+</sup>	Inverting input of the transmit input amplifier.  Non-inverting input of the transmit input amplifier.
	synchronous with $MCLK_X$ for best performance. When $MCLK_R$ is connected continuously low, $MCLK_X$ is selected for all internal timing. When $MCLK_R$ is connected continuously high, the device is powered down.	$V_BB$	Negative power supply pin. $V_{BB} = -5V \pm 5\%$ .

### **Functional Description**

### POWER-UP

When power is first applied, power-on reset circuitry initializes the COMBOTM and places it into a power-down state. All non-essential circuits are deactivated and the  $D_X$ ,  $VF_RO$ ,  $VPO^-$  and  $VPO^+$  outputs are put in high impedance states. To power-up the device, a logical low level or clock must be applied to the MCLKR/PDN pin and FS\_X and/or FS\_R pulses must be present. Thus, 2 power-down control modes are available. The first is to pull the MCLKR/PDN pin high; the alternative is to hold both FS\_X and FS\_R inputs continuously low—the device will power-down approximately 2 ms after the last FS\_X or FS\_R pulse. Power-up will occur on the first FS\_X or FS\_R pulse. The TRI-STATE PCM data output,  $D_X$ , will remain in the high impedance state until the second FS\_X pulse.

### SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to MCLK\_X and the MCLK\_B/PDN pin can be used as a power-down control. A low level on MCLK\_B/PDN powers up the device and a high level powers down the device. In either case, MCLK\_X will be selected as the master clock for both the transmit and receive circuits. A bit clock must also be applied to BCLK\_X and the BCLK\_B/CLKSEL can be used to select the proper internal divider for a master clock of 1.536 MHz, 1.544 MHz or 2.048 MHz. For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame.

With a fixed level on the BCLK $_{\rm R}$ /CLKSEL pin, BLCK $_{\rm X}$  will be selected as the bit clock for both the transmit and receive directions. Table I indicates the frequencies of operation which can be selected, depending on the state of BCLK $_{\rm R}$ /CLKSEL. In this synchronous mode, the bit clock, BCLK $_{\rm X}$ , may be from 64 kHz to 2.048 MHz, but must be synchronous with MCLK $_{\rm X}$ .

Each FS $_X$  pulse begins the encoding cycle and the PCM data from the previous encode cycle is shifted out of the enabled D $_X$  output on the positive edge of BCLK $_X$ . After 8 bit clock periods, the TRI-STATE D $_X$  output is returned to a high impedance state. With an FS $_R$  pulse, PCM data is latched via the D $_R$  input on the negative edge of BCLK $_X$  (or BCLK $_R$  if running). FS $_X$  and FS $_R$  must be synchronous with MCLK $_X$  $_R$ .

TABLE I. Selection of Master Clock Frequencies

TABLE I. Selection of Master Clock Frequencies								
BCLK <sub>R</sub> /CLKSEL	Master Clock Frequency Selected							
BOLKH/OLKSEL	TP3067	TP3064						
Clocked	2.048 MHz	1.536 MHz or						
		1.544 MHz						
0	1.536 MHz or	2.048 MHz						
	1.544 MHz							
1	2.048 MHz	1.536 MHz or						
		1.544 MHz						

### **ASYNCHRONOUS OPERATION**

For asynchronous operation, separate transmit and receive clocks may be applied. MCLK $_{\rm X}$  and MCLK $_{\rm R}$  must be 2.048 MHz for the TP3067, or 1.536 MHZ, 1.544 MHz for the TP3064, and need not be synchronous. For best transmis-

sion performance, however, MCLK $_{\rm R}$  should be synchronous with MCLK $_{\rm X}$ , which is easily achieved by applying only static logic levels to the MCLK $_{\rm R}$ /PDN pin. This will automatically connect MCLK $_{\rm X}$  to all internal MCLK $_{\rm R}$  functions (see Pin Description). For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame. FS $_{\rm X}$  starts each encoding cycle and must be synchronous with MCLK $_{\rm X}$  and BCLK $_{\rm X}$ . FS $_{\rm R}$  starts each decoding cycle and must be synchronous with BCLK $_{\rm R}$ . BCLK $_{\rm R}$  must be a clock, the logic levels shown in Table I are not valid in asynchronous mode. BCLK $_{\rm X}$  and BCLK $_{\rm R}$  may operate from 64 kHz to 2 048 MHz

### SHORT FRAME SYNC OPERATION

The COMBO can utilize either a short frame sync pulse (the same as the TP3020/21 CODECs) or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses, FSX and FS<sub>R</sub>, must be one bit clock period long, with timing relationships specified in Figure 2. With FSX high during a falling edge of BCLKX, the next rising edge of BCLKX enables the Dy TRI-STATE output buffer, which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the DX output. With FSR high during a falling edge of BCLKR (BCLKX in synchronous mode), the next falling edge of BCLKR latches in the sign bit. The following seven falling edges latch in the seven remaining bits. All devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

### LONG FRAME SYNC OPERATION

To use the long (TP5116A/56 CODECs) frame mode, both the frame sync pulses, FS<sub>X</sub> and FS<sub>R</sub>, must be three or more bit clock periods long, with timing relationships specified in Figure 3. Based on the transmit frame sync, FS<sub>X</sub>, the COM-BO will sense whether short or long frame sync pulses are being used. For 64 kHz operation, the frame sync pulse must be kept low for a minimum of 160 ns. The Dx TRI-STATE output buffer is enabled with the rising edge of FSX or the rising edge of BCLKX, whichever comes later, and the first bit clocked out is the sign bit. The following seven BCLK<sub>X</sub> rising edges clock out the remaining seven bits. The D<sub>X</sub> output is disabled by the falling BCLK<sub>X</sub> edge following the eighth rising edge, or by  $FS_X$  going low, whichever comes later. A rising edge on the receive frame sync pulse, FS<sub>R</sub>, will cause the PCM data at D<sub>R</sub> to be latched in on the next eight falling edges of BCLKR(BCLKX in synchronous mode). All devices may utilize the long frame sync pulse in synchronous or asynchronous mode.

### TRANSMIT SECTION

The transmit section input is an operational amplifier with provision for gain adjustment using two external resistors, see Figure 4. The low noise and wide bandwidth allow gains in excess of 20 dB across the audio passband to be realized. The op amp drives a unity-gain filter consisting of RC active pre-filter, followed by an eighth order switched-capacitor bandpass filter clocked at 256 kHz. The output of this filter directly drives the encoder sample-and-hold circuit. The A/D is of companding type according to  $\mu$ -law (TP3064) or A-law (TP3067) coding conventions. A precision voltage reference is trimmed in manufacturing to provide an input overload (tMAX) of nominally 2.5V peak (see

### Functional Description (Continued)

table of Transmission Characteristics). The FS $_{\rm X}$  frame sync pulse controls the sampling of the filter output, and then the successive-approximation encoding cycle begins. The 8-bit code is then loaded into a buffer and shifted out through D $_{\rm X}$  at the next FS $_{\rm X}$  pulse. The total encoding delay will be approximately 165  $\mu$ s (due to the transmit filter) plus 125  $\mu$ s (due to encoding delay), which totals 290  $\mu$ s. Any offset voltage due to the filters or comparator is cancelled by sign bit integration.

### RECEIVE SECTION

The receive section consists of an expanding DAC which drives a fifth order switched-capacitor low pass filter clocked at 256 kHz. The decoder is A-law (TP3067) or  $\mu$ -law (TP3064) and the 5th order low pass filter corrects for the sin x/x attenuation due to the 8 kHz sample/hold. The filter is then followed by a 2nd order RC active post-filter with its output at VF $_R$ O. The receive section is unity-gain, but gain can be added by using the power amplifiers. Upon the occurrence of FS $_R$ , the data at the  $D_R$  input is clocked in on the falling edge of the next eight BCLK $_R$  (BCLK $_X$ ) peri-

ods. At the end of the decoder time slot, the decoding cycle begins, and 10  $\mu s$  later the decoder DAC output is updated. The total decoder delay is  $\sim$  10  $\mu s$  (decoder update) plus 110  $\mu s$  (filter delay) plus 62.5  $\mu s$  (½ frame), which gives approximately 180  $\mu s$ .

### **RECEIVE POWER AMPLIFIERS**

Two inverting mode power amplifiers are provided for directly driving a matched line interface transformer. The gain of the first power amplifier can be adjusted to boost the  $\pm 2.5 V$  peak output signal from the receive filter up to  $\pm 3.3 V$  peak into an unbalanced  $300\Omega$  load, or  $\pm 4.0 V$  into an unbalanced 15  $\rm k\Omega$  load. The second power amplifier is internally connected in unity-gain inverting mode to give 6 dB of signal gain for balanced loads.

Maximum power transfer to a 600 $\Omega$  subscriber line termination is obtained by differentially driving a balanced transformer with a  $\sqrt{2}$ :1 turns ratio, as shown in *Figure 4*. A total peak power of 15.6 dBm can be delivered to the load plus termination.

### ENCODING FORMAT AT $D_X$ OUTPUT

	<b>TP3064</b> μ <b>-Law</b>						(I	nclude		_aw	versio	n)				
$V_{IN} = +Full-Scale$	1	0	0	0	0	0	0	0	1	0	1	0	1	0	1	0
$V_{IN} = 0V$	∫1	1	1	1	1	1	1	1	1	1	0	1	0	1	0	1
	lo	1	1	1	1	1	1	1	0	1	0	1	0	1	0	1
$V_{IN} = -Full-Scale$	0	0	0	0	0	0	0	0	0	0	1	0	1	0	1	0

### **Absolute Maximum Ratings**

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

 $\begin{array}{c} {\rm V_{CC}~to~GNDA} & 7{\rm V} \\ {\rm V_{BB}~to~GNDA} & -7{\rm V} \\ {\rm Voltage~at~any~Analog~Input} \end{array}$ 

or Output  $V_{CC} + 0.3V$  to  $V_{BB} - 0.3V$ 

Voltage at any Digital Input or Output

Operating Temperature Range
Storage Temperature Range
Lead Temp. (Soldering, 10 sec.)

ESD (Human Body Model) J

ESD (Human Body Model) N

Latch-Up Immunity

VCC+0.3V to GNDA-0.3V

-25°C to +125°C

-65°C to +150°C

300°C

300°C

1000V

**Electrical Characteristics** Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC} = +5.0V \pm 5\%$ ,  $V_{BB} = -5.0V \pm 5\%$ ;  $T_A = 0^{\circ}C$  to  $70^{\circ}C$  by correlation with 100% electrical testing at  $T_A = 25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. All signals referenced to GNDA. Typicals specified at  $V_{CC} = +5.0V$ ,  $V_{BB} = -5.0V$ ,  $T_A = 25^{\circ}C$ .

Symbol	Parameter	Conditions	Min	Тур	Max	Units		
POWER DISSIPATION (ALL DEVICES)								
I <sub>CC</sub> 0	Power-Down Current	(Note)		0.5	1.5	mA		
I <sub>BB</sub> 0	Power-Down Current	(Note)		0.05	0.3	mA		
I <sub>CC</sub> 1	Active Current	VPI=0V; VF <sub>R</sub> O, VPO+ and VPO- unloaded		7.0	10.0	mA		
I <sub>BB</sub> 1	Active Current	VPI=0V; VF <sub>R</sub> O, VPO+ and VPO- unloaded		7.0	10.0	mA		
DIGITAL	INTERFACE							
V <sub>IL</sub>	Input Low Voltage				0.6	٧		
V <sub>IH</sub>	Input High Voltage		2.2			٧		
V <sub>OL</sub>	Output Low Voltage	$D_{X}$ , $I_{L} = 3.2 \text{ mA}$ $\overline{TS_{X}}$ , $I_{L} = 3.2 \text{ mA}$ , Open Drain			0.4 0.4	V V		
V <sub>OH</sub>	Output High Voltage	$D_X$ , $I_H = -3.2 \text{ mA}$	2.4			٧		
I <sub>IL</sub>	Input Low Current	GNDA≤V <sub>IN</sub> ≤V <sub>IL</sub> , All Digital Inputs	-10		10	μΑ		
I <sub>IH</sub>	Input High Current	V <sub>IH</sub> ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>	-10		10	μΑ		
loz	Output Current in High Impedance State (TRI-STATE)	$D_X$ , $GNDA \le V_O \le V_{CC}$	- 10		10	μΑ		

Note: I<sub>CC0</sub> and I<sub>BB0</sub> are measured after first achieving a power-up state.

### **Electrical Characteristics** (Continued)

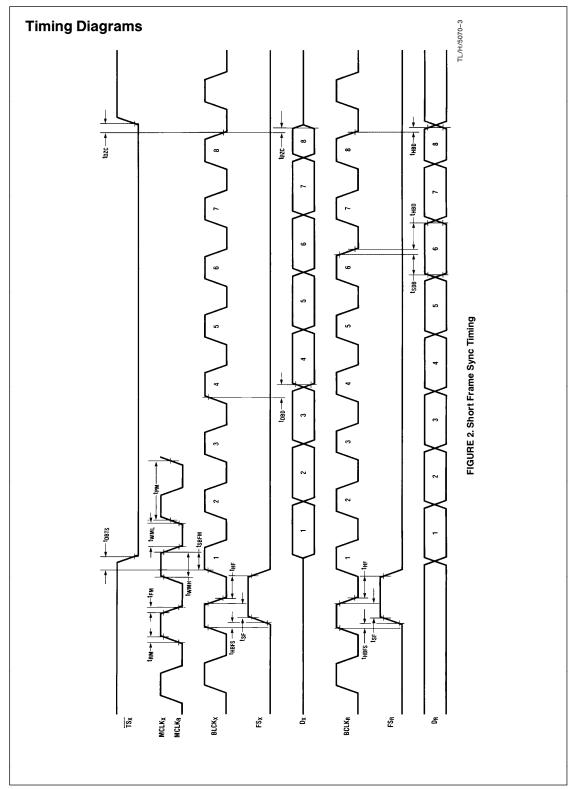
Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC}=+5.0V\pm5\%$ ,  $V_{BB}=-5.0V\pm5\%$ ;  $T_A=0^{\circ}C$  to 70°C by correlation with 100% electrical testing at  $T_A=25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. All signals referenced to GNDA. Typicals specified at  $V_{CC}=+5.0V$ ,  $V_{BB}=-5.0V$ ,  $V_{AB}=-5.0V$ 

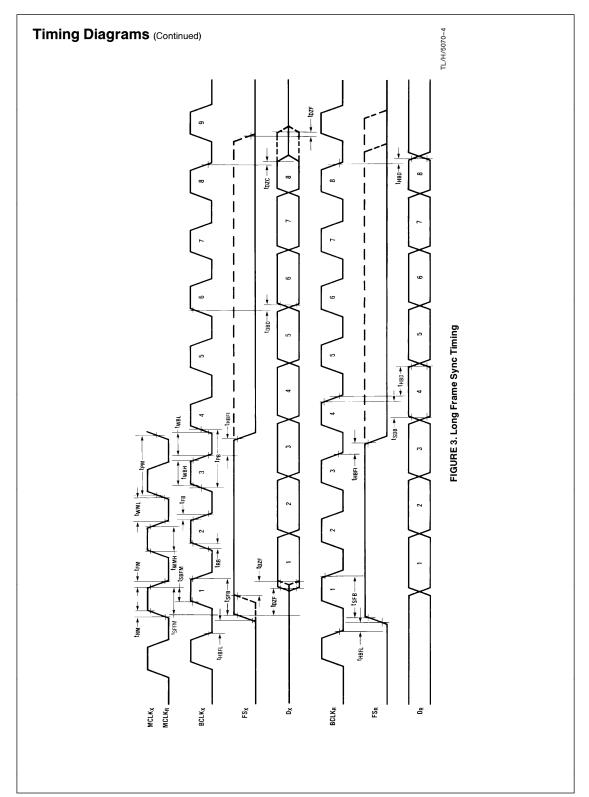
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
ANALOG IN	NTERFACE WITH TRANSMIT INPU	T AMPLIFIER (ALL DEVICES)	•			
I <sub>I</sub> XA	Input Leakage Current	$-2.5V \le V \le +2.5V$ , VF <sub>X</sub> I + or VF <sub>X</sub> I -	-200		200	nA
R <sub>I</sub> XA	Input Resistance	$-2.5V \le V \le +2.5V$ , VF <sub>X</sub> I + or VF <sub>X</sub> I -	10			МΩ
R <sub>O</sub> XA	Output Resistance	Closed Loop, Unity Gain		1	3	Ω
R <sub>L</sub> XA	Load Resistance	GS <sub>X</sub>	10			kΩ
C <sub>L</sub> XA	Load Capacitance	GS <sub>X</sub>			50	pF
V <sub>O</sub> XA	Output Dynamic Range	$GS_X$ , $R_L \ge 10 \text{ k}\Omega$	-2.8		+ 2.8	V
A <sub>V</sub> XA	Voltage Gain	VF <sub>X</sub> I+ to GS <sub>X</sub>	5000			٧/١
F <sub>U</sub> XA	Unity-Gain Bandwidth		1	2		МН
V <sub>OS</sub> XA	Offset Voltage		-20		20	m\
V <sub>CM</sub> XA	Common-Mode Voltage	CMRRXA > 60 dB	- 2.5		2.5	٧
CMRRXA	Common-Mode Rejection Ratio	DC Test	60			dE
PSRRXA	Power Supply Rejection Ratio	DC Test	60			dE
ANALOG IN	NTERFACE WITH RECEIVE FILTER	R (ALL DEVICES)	•			
R <sub>O</sub> RF	Output Resistance	Pin VF <sub>R</sub> O		1	3	Ω
R <sub>L</sub> RF	Load Resistance	VF <sub>R</sub> O = ± 2.5V	10			kΩ
C <sub>L</sub> RF	Load Capacitance	Connect from VF <sub>R</sub> O to GNDA			25	pF
VOS <sub>R</sub> O	Output DC Offset Voltage	Measure from VF <sub>R</sub> O to GNDA	-200		200	m\
ANALOG IN	NTERFACE WITH POWER AMPLIF	IERS (ALL DEVICES)				
IPI	Input Leakage Current	-1.0V≤VPI≤1.0V	- 100		100	nA
RIPI	Input Resistance	-1.0V≤VPI≤1.0V	10			M
VIOS	Input Offset Voltage		-25		25	m۱
ROP	Output Resistance	Inverting Unity-Gain at VPO+ or VPO-		1		Ω
F <sub>C</sub>	Unity-Gain Bandwidth	Open Loop (VPO <sup>-</sup> )	•	400		kH:
C <sub>L</sub> P	Load Capacitance				100	рF
GA <sub>P</sub> +	Gain from VPO - to VPO +	$R_L = 600\Omega \text{ VPO}^+ \text{ to VPO}^-$ Level at $VPO^- = 1.77 \text{ Vrms}$		-1		V/'
PSRR <sub>P</sub>	Power Supply Rejection of V <sub>CC</sub> or V <sub>BB</sub>	VPO <sup>-</sup> Connected to VPI 0 kHz - 4 kHz 4 kHz - 50 kHz	60 36			dE dE
R <sub>L</sub> P	Load Resistance	Connect from VPO+ to VPO-	600			Ω

### **Timing Specifications**

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC} = +5.0V \pm 5\%$ ,  $V_{BB} = -5.0V \pm 5\%$ ,  $T_A = 0^{\circ}C$  to  $70^{\circ}C$  by correlation with 100% electrical testing at  $T_A = 25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. All signals are referenced to GNDA. Typicals specified at  $V_{CC} = +5.0V$ ,  $V_{BB} = -5.0V$ ,  $V_{AB} = -5.0V$ 

Symbol	Parameter	Conditions	Min	Тур	Max	Units
1/t <sub>PM</sub>	Frequency of Master Clock			1.536		MHz
		MCLK: and MCLK-		1.544 <b>2.048</b>		MHz MHz
t	Rise Time of Master Clock	MCLK <sub>X</sub> and MCLK <sub>R</sub> MCLK <sub>X</sub> and MCLK <sub>B</sub>		2.048	50	
t <sub>RM</sub>	Fall Time of Master Clock				50	ns ns
t <sub>FM</sub>	Period Bit of Clock	MCLK <sub>X</sub> and MCLK <sub>R</sub>	485	488	15725	
t <sub>PB</sub>		DCLK and DCLK	465	400	50	ns
t <sub>RB</sub>	Rise Time of Bit Clock	BCLK <sub>X</sub> and BCLK <sub>R</sub>			50	ns
t <sub>FB</sub>	Fall Time of Bit Clock	BCLK <sub>X</sub> and BCLK <sub>R</sub>	460		50	ns
t <sub>WMH</sub>	Width of Master Clock High	MCLK <sub>X</sub> and MCLK <sub>R</sub>	160			ns
t <sub>WML</sub>	Width of Master Clock Low	MCLK <sub>X</sub> and MCLK <sub>R</sub>	160			ns
t <sub>SBFM</sub>	Set-Up Time from BCLK <sub>X</sub> High to MCLK <sub>X</sub> Falling Edge		100			ns
t <sub>SFFM</sub>	Set-Up Time from $FS_X$ High to $MCLK_X$ Falling Edge	Long Frame Only	100			ns
t <sub>WBH</sub>	Width of Bit Clock High		160			ns
t <sub>WBL</sub>	Width of Bit Clock Low		160			ns
t <sub>HBFL</sub>	Holding Time from Bit Clock Low to Frame Sync	Long Frame Only	0			ns
t <sub>HBFS</sub>	Holding Time from Bit Clock High to Frame Sync	Short Frame Only	0			ns
t <sub>SFB</sub>	Set-Up Time for Frame Sync to Bit Clock Low	Long Frame Only	80			ns
t <sub>DBD</sub>	Delay Time from BCLK <sub>X</sub> High to Data Valid	Load = 150 pF plus 2 LSTTL Loads	0		180	ns
t <sub>DBTS</sub>	Delay Time to TS <sub>X</sub> Low	Load = 150 pF plus 2 LSTTL Loads			140	ns
t <sub>DZC</sub>	Delay Time from BCLK <sub>X</sub> Low to Data Output Disabled		50		165	ns
t <sub>DZF</sub>	Delay Time to Valid Data from $FS_X$ or $BCLK_X$ , Whichever Comes Later	C <sub>L</sub> =0 pF to 150 pF	20		165	ns
t <sub>SDB</sub>	Set-Up Time from $D_R$ Valid to $BCLK_{R/X}$ Low		50			ns
t <sub>HBD</sub>	Hold Time from $\operatorname{BCLK}_{R/X}$ Low to $\operatorname{D}_R$ Invalid		50			ns
t <sub>SF</sub>	Set-Up Time from FS <sub>X/R</sub> to BCLK <sub>X/R</sub> Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	50			ns
t <sub>HF</sub>	Hold Time from BCLK <sub>X/R</sub> Low to FS <sub>X/R</sub> Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	100			ns
t <sub>HBFI</sub>	Hold Time from 3rd Period of Bit Clock Low to Frame Sync (FS <sub>X</sub> or FS <sub>R</sub> )	Long Frame Sync Pulse (from 3 to 8 Bit Clock Periods Long)	100			ns
t <sub>WFL</sub>	Minimum Width of the Frame Sync Pulse (Low Level)	64k Bit/s Operating Mode	160			ns





### **Transmission Characteristics**

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC}=+5.0V\pm5\%$ ,  $V_{BB}=-5.0V\pm5\%$ ;  $T_A=0^{\circ}C$  to 70°C by correlation with 100% electrical testing at  $T_A=25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz,  $V_{IN}=0$  dbm0, transmit input amplifier connected for unity gain non-inverting. Typicals specified at  $V_{CC}=+5.0V$ ,  $V_{BB}=-5.0V$ ,  $T_A=25^{\circ}C$ .

Symbol	Parameter	Conditions	Min	Тур	Max	Units
AMPLITU	JDE RESPONSE					
	Absolute Levels (Definition of nominal gain)	Nominal 0 dBm0 Level is 4 dBm (600 $\Omega$ ) 0 dBm0		1.2276		Vrms
t <sub>MAX</sub>	Virtual Decision Value Defined per CCITT Rec. G711	Max Transmit Overload Level TP3064 (3.17 dBm0) TP3067 (3.14 dBm0)		2.501 2.492		V <sub>PK</sub> V <sub>PK</sub>
G <sub>XA</sub>	Transmit Gain, Absolute	$T_A = 25^{\circ}C, V_{CC} = 5V, V_{BB} = -5V$	-0.15		0.15	dB
G <sub>XR</sub>	Transmit Gain, Relative to G <sub>XA</sub>	f= 16 Hz f= 50 Hz f= 60 Hz f= 200 Hz f= 300 Hz-3000 Hz f= 3300 Hz f= 3400 Hz f= 4000 Hz f= 4600 Hz and Up, Measure Response from 0 Hz to 4000 Hz	-1.8 -0.15 -0.35 -0.7		-40 -30 -26 -0.1 0.15 0.05 0 -14 -32	dB dB dB dB dB dB dB
$G_XAT$	Absolute Transmit Gain Variation with Temperature	Relative to G <sub>XA</sub>	-0.1		0.1	dB
G <sub>XAV</sub>	Absolute Transmit Gain Variation with Supply Voltage	Relative to G <sub>XA</sub>	-0.05		0.05	dB
G <sub>XRL</sub>	Transmit Gain Variations with Level	Sinusoidal Test Method Reference Level = $-10$ dBm0 VF <sub>X</sub> I + = $-40$ dBm0 to $+3$ dBm0 VF <sub>X</sub> I + = $-50$ dBm0 to $-40$ dBm0 VF <sub>X</sub> I + = $-55$ dBm0 to $-50$ dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB dB dB
G <sub>RA</sub>	Receive Gain, Absolute	T <sub>A</sub> =25°C, V <sub>CC</sub> =5V, V <sub>BB</sub> =-5V Input=Digital Code Sequence for 0 dBm0 Signal	-0.15		0.15	dB
G <sub>RR</sub>	Receive Gain, Relative to G <sub>RA</sub>	f = 0 Hz to 3000 Hz f = 3300 Hz f = 3400 Hz f = 4000 Hz	-0.15 -0.35 -0.7		0.15 0.05 0 -14	dB dB dB dB
G <sub>RAT</sub>	Absolute Receive Gain Variation with Temperature	Relative to G <sub>RA</sub>	-0.1		0.1	dB
G <sub>RAV</sub>	Absolute Receive Gain Variation with Supply Voltage	Relative to G <sub>RA</sub>	-0.05		0.05	dB
G <sub>RRL</sub>	Receive Gain Variations with Level	Sinusoidal Test Method; Reference Input PCM Code Corresponds to an Ideally Encoded — 10 dBm0 Signal PCM Level = -40 dBm0 to +3 dBm0 PCM Level = -50 dBm0 to -40 dBm0 PCM Level = -55 dBm0 to -50 dBm0	- 0.2 - 0.4 - 1.2		0.2 0.4 1.2	dB dB dB
V <sub>RO</sub>	Receive Filter Output at VF <sub>B</sub> O	RL = 10 kΩ	-2.5		2.5	V

### **Transmission Characteristics** (Continued)

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC} = +5.0V \pm 5\%$ ,  $V_{BB} = -5.0V \pm 5\%$ ;  $T_A = 0^{\circ}C$  to 70°C by correlation with 100% electrical testing at  $T_A = 25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz,  $V_{IN} = 0$  dbm0, transmit input amplifier connected for unity gain non-inverting. Typicals specified at  $V_{CC} = +5.0V$ ,  $V_{BB} = -5.0V$ ,  $T_A = 25^{\circ}C$ .

Symbol	Parameter	Conditions	Min	Тур	Max	Units
ENVELOP	E DELAY DISTORTION WITH FREQU	JENCY				
D <sub>XA</sub>	Transmit Delay, Absolute	f=1600 Hz		290	315	μs
D <sub>XR</sub>	Transmit Delay, Relative to DXA	f=500 Hz-600 Hz		195	220	μS
711	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	f=600 Hz-800 Hz		120	145	μs
		f=800 Hz-1000 Hz		50	75	μs
		f=1000 Hz-1600 Hz		20	40	μs
		f=1600 Hz-2600 Hz		55	75	μs
		f=2600 Hz-2800 Hz		80	105	μs
		f=2800 Hz-3000 Hz		130	155	μs
D <sub>RA</sub>	Receive Delay, Absolute	f=1600 Hz		180	200	μs
D <sub>RR</sub>	Receive Delay, Relative to DRA	f=500 Hz-1000 Hz	-40	-25		μs
-1111		f=1000 Hz-1600 Hz	-30	-20		μs
		f=1600 Hz-2600 Hz		70	90	μs
		f=2600 Hz-2800 Hz		100	125	μS
		f=2800 Hz-3000 Hz		145	175	μS
NOISE						,
N <sub>XC</sub>	Transmit Noise, C Message	TP3064 (Note 1)		12	15	dBrnC0
,,,,	Weighted	, ,				
$N_{XP}$	Transmit Noise, Psophometric	TP3067 (Note 1)		-74	<b>-67</b>	dBm0p
	Weighted					
N <sub>RC</sub>	Receive Noise, C Message	PCM Code Equals Alternating				
	Weighted	Positive and Negative Zero				
		TP3064		8	11	dBrnCO
$N_{RP}$	Receive Noise, Psophometric	PCM Code Equals Positive				
	Weighted	Zero				
		TP3067		-82	<b>-79</b>	dBm0p
N <sub>RS</sub>	Noise, Single Frequency	f=0 kHz to 100 kHz, Loop Around			-53	dBm0
		Measurement, VF <sub>X</sub> I <sup>+</sup> = 0 Vrms				
PPSRX	Positive Power Supply Rejection,	$V_{CC} = 5.0 V_{DC} + 100 \text{ mVrms}$				
	Transmit	f=0 kHz-50 kHz (Note 2)	40			dBC
NPSRX	Negative Power Supply Rejection,	$V_{BB} = -5.0 V_{DC} + 100 \text{ mVrms}$	40			400
	Transmit	f=0 kHz-50 kHz (Note 2)	40			dBC
PPSR <sub>R</sub>	Positive Power Supply Rejection,	PCM Code Equals Positive Zero				
	Receive	V <sub>CC</sub> =5.0 V <sub>DC</sub> +100 mVrms				
		Measure VF <sub>R</sub> O				
		f=0 Hz-4000 Hz	38			dBC
		f=4 kHz-50 kHz	25			dB
NPSR <sub>R</sub>	Negative Power Supply Rejection,	PCM Code Equals Positive Zero				
	Receive	$V_{BB} = -5.0 V_{DC} + 100 \text{ mVrms}$				
		Measure VF <sub>R</sub> O				
		f=0 Hz-4000 Hz	40			dBC
		f=4 kHz-25 kHz	40			dB
		f=25 kHz-50 kHz	36			dB
sos	Spurious Out-of-Band Signals	0 dBm0, 300 Hz - 3400 Hz Input				
	at the Channel Output	PCM Code Applied at DR				
	·	Measure Individual Image Signals at				
		VF <sub>R</sub> O				
		4600 Hz-7600 Hz			<b>-32</b>	dB
	1		I	l	-40	dB
		7600 Hz-8400 Hz			40	u u D

### **Transmission Characteristics** (Continued)

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC} = +5.0V \pm 5\%$ ,  $V_{BB} = -5.0V \pm 5\%$ ;  $T_A = 0^{\circ}C$  to 70°C by correlation with 100% electrical testing at  $T_A = 25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz,  $V_{IN} = 0$  dbm0, transmit input amplifier connected for unity gain non-inverting. Typicals specified at  $V_{CC} = +5.0V$ ,  $V_{BB} = -5.0V$ ,  $T_A = 25^{\circ}C$ .

Symbol	Parameter	Conditions	Min	Тур	Max	Units
DISTORT	ION					
STD <sub>X</sub> , STD <sub>R</sub>	Signal to Total Distortion Transmit or Receive Half-Channel	Sinusoidal Test Method (Note 3)  Level = 3.0 dBm0 = 0 dBm0 to -30 dBm0 = -40 dBm0 XMT RCV = -55 dBm0 XMT	33 36 29 30 14 15			dBC dBC dBC dBC dBC dBC
SFD <sub>X</sub>	Single Frequency Distortion, Transmit				<b>-46</b>	dB
SFD <sub>R</sub>	Single Frequency Distortion, Receive				<b>-46</b>	dB
IMD	Intermodulation Distortion	Loop Around Measurement, $VF_XI^+ = -4$ dBm0 to $-21$ dBm0, Two Frequencies in the Range 300 Hz $-3400$ Hz			-41	dB
CROSSTA	ALK					
CT <sub>X-R</sub>	Transmit to Receive Crosstalk	f=300 Hz-3000 Hz D <sub>R</sub> =Quiet PCM Code		-90	<b>-75</b>	dB
CT <sub>R-X</sub>	Receive to Transmit Crosstalk	f=300 Hz-3000 Hz, VF <sub>X</sub> I=0V (Note 2)		-90	<b>-70</b>	dB
POWER A	AMPLIFIERS					
V <sub>O</sub> PA	Maximum 0 dBm0 Level (Better than ±0.1 dB Linearity over the Range -10 dBm0 to +3 dBm0)	Balanced Load, R <sub>L</sub> Connected Betweer VPO+ and VPO $R_L = 600\Omega$ $R_L = 1200\Omega$	<b>3.3</b> 3.5			Vrms Vrms
S/D <sub>P</sub>	Signal/Distortion	$R_L = 600\Omega$	50			dB

Note 1: Measured by extrapolation from the distortion test result at  $-50\ \text{dBm0}.$ 

Note 2: PPSR\_X, NPSR\_X, and CT\_{R-X} are measured with a -50 dBm0 activation signal applied to VF\_XI  $^+.$ 

Note 3: TP3064 is measured using C message weighted filter. TP3067 is measured using psophometric weighted filter.

### **Applications Information**

### **POWER SUPPLIES**

While the pins of the TP3060 family are well protected against electrical misuse, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed circuit board may be plugged into a "hot" socket with power and clocks already present, an extra long ground pin in the connector should be used

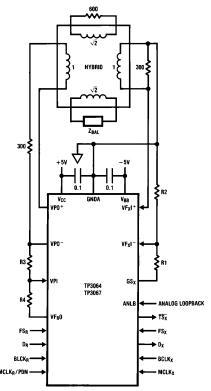
All ground connections to each device should meet at a common point as close as possible to the GNDA pin. This

minimizes the interaction of ground return currents flowing through a common bus impedance. 0.1  $\mu F$  supply decoupling capacitors should be connected from this common ground point to  $V_{CC}$  and  $V_{BB},$  as close to the device as possible.

For best performance, the ground point of each CODEC/FILTER on a card should be connected to a common card ground in "STAR" formation, rather than via a ground bus. This common ground point should be decoupled to  $V_{CC}$  and  $V_{BB}$  with 10  $\mu F$  capacitors.

Note: See Application Note 370 for further details

### **Typical Asynchronous Application**



Note 1: Transmit gain  $=20 \times log \left(\frac{R1+R2}{R2}\right)$ ,  $(R1+R2) \geq 10 \ k\Omega$ Note 2: Receive gain  $=20 \times log \left(\frac{2 \times R3}{R4}\right)$ ,  $R4 \geq 10 \ k\Omega$ 

FIGURE 4

### **Definitions and Timing Conventions**

### **DEFINITIONS**

VOL

V<sub>IH</sub> V<sub>IH</sub> is the d.c. input level above which an input level is guaranteed to appear

as a logical one. This parameter is to be measured by performing a functional test at reduced clock speeds and nominal timing, (i.e. not minimum setup and hold times or output strobes), with the high level of all driving signals set to V<sub>IH</sub> and maximum supply voltages applied to

the device

V<sub>IL</sub> is the d.c. input level below which

an input level is guaranteed to appear as a logical zero to the device. This parameter is measured in the same manner as  $V_{IH}$  but with all driving signal low levels set to  $V_{IL}$  and minimum supply voltages applied to

the device.

 $V_{OH}$  V<sub>OH</sub> is the minimum d.c. output level

to which an output placed in a logical one state will converge when loaded at the maximum specified load current.  $V_{OL}$  is the maximum d.c. output level

vol. is the maximum c.c. output level to which an output placed in a logical zero state will converge when loaded at the maximum specified load current.

Threshold Region The threshold region is the range of input voltages between  $V_{IL}$  and  $V_{IH}$ .

Valid Signal A signal is Valid if it is in one of the valid logic states, (i.e. above V<sub>IH</sub> or

below V<sub>IL</sub>). In timing specifiations, a signal is deemed valid at the instant it

enters a valid state.

Invalid Signal A signal is Invalid if it is not in a valid

logic state, i.e. when it is in in the threshold region between  $V_{IL}$  and  $V_{IH}$ . In timing specifications, a signal is deemed invalid at the instant it enters

the threshold region.

### **TIMING CONVENTIONS**

For the purposes of this timing specification, the following

conventions apply:

Input Signals All input signals may be characterized

as:  $V_L = 0.4V$ ,  $V_H = 2.4V$ ,  $t_R < 10$  ns,

 $t_F < 10 \text{ ns.}$ 

Period The period of clock signal is designated as t<sub>Pxx</sub> where xx

represents the mnemonic of the clock

signal being specified.

Rise Time Rise times are designated as t<sub>Ryy</sub>,

where yy represents a mnemonić of the signal whose rise time is being specified.  $t_{Ryy}$  is measured from  $V_{IL}$  to

 $V_{IH}$ .

Fall Time Fall times are designated as t<sub>Fyy</sub>, where yy represents a mnemonic of

where yy represents a mnemonic of the signal whose fall time is being specified. t<sub>Fyy</sub> is measured from V<sub>IH</sub> to V<sub>I</sub>.

Pulse Width High The high pulse width is designated as

t<sub>WzzH</sub>, where zz represents the mnemonic of the input or output signal whose pulse width is being specified. High pulse widths are measured from

V<sub>IH</sub> to V<sub>IH</sub>.

Pulse Width Low The low pulse width is designated as

t<sub>WzzL</sub>, where zz represents the mnemonic of the input or output signal whose pulse width is being specified. Low pulse widths are measured from

VII to VII.

Setup Time Setup times are designated as t<sub>Swwxx</sub>,

where ww represents the mnemonic of the input signal whose setup time is being specified relative to a clock or strobe input represented by mnemonic xx. Setup times are measured from the

ww Valid to xx Invalid.

Hold Time Hold times are designated as t<sub>Hxxww</sub>, where ww represents the mnemonic of

where ww represents the mnemonic of the input signal whose hold time is being specified relative to a clock or strobe input represented by mnemonic xx. Hold times are measured from xx

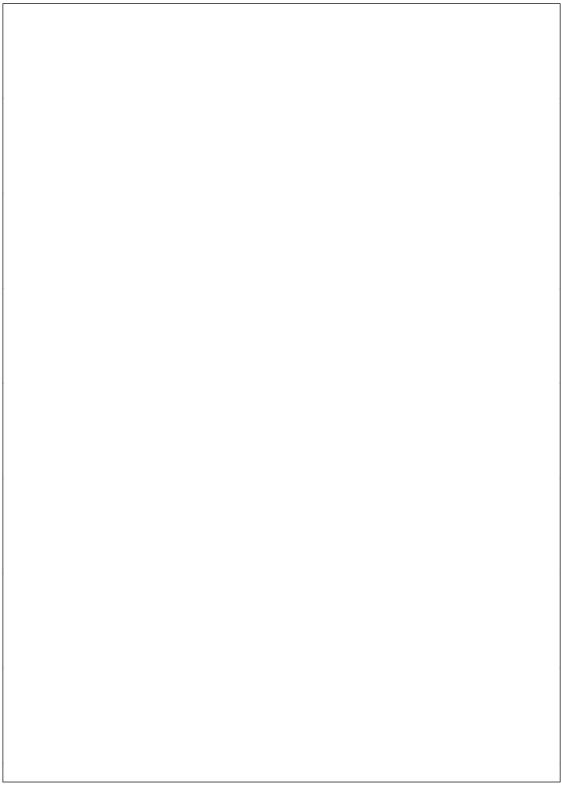
Valid to ww Invalid.

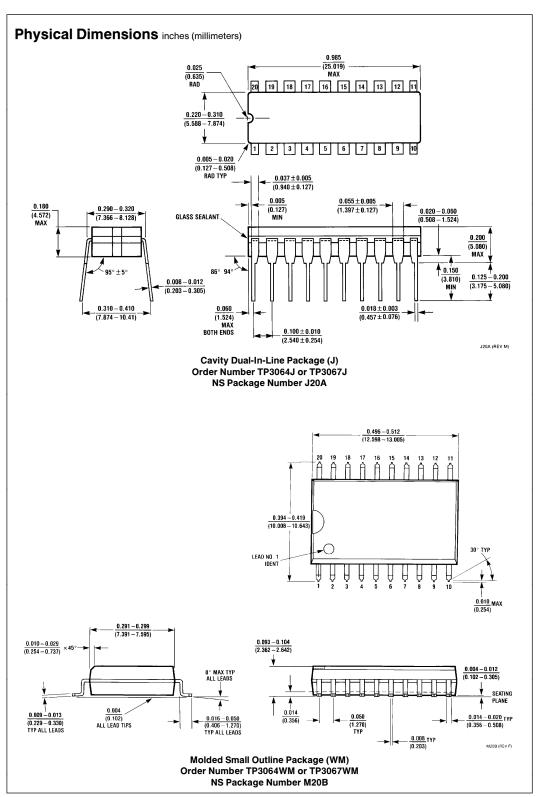
Delay Time Delay times are designated as t<sub>Dxxyy</sub>

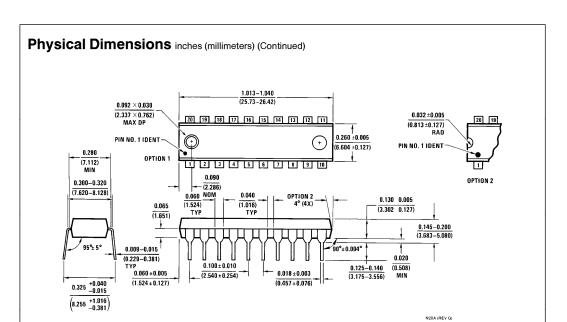
Hi to Low, where xx represents the mnemonic of the input reference signal and yy represents the mnemonic of the output signal whose timing is being specified relative to xx. The mnemonic may optionally be terminated by an H or L to specify the high going or low going transition of the output signal. Maximum delay times are measured from xx Valid to yy Valid. Minimum delay times are measured from xx Valid to yy Invalid.

This parameter is tested under the load conditions specified in the Conditions column of the Timing Specifications section of this data

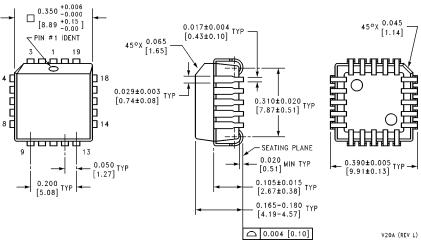
sheet.







Molded Dual-In-Line Package (N) Order Number TP3064N or TP3067N NS Package Number N20A



Plastic Chip Carrier (V) Order Number TP3064V or TP3067V NS Package Number V20A

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